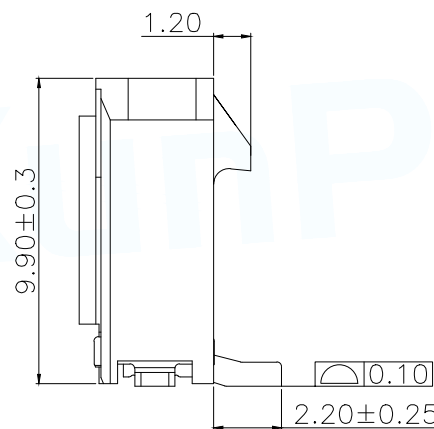
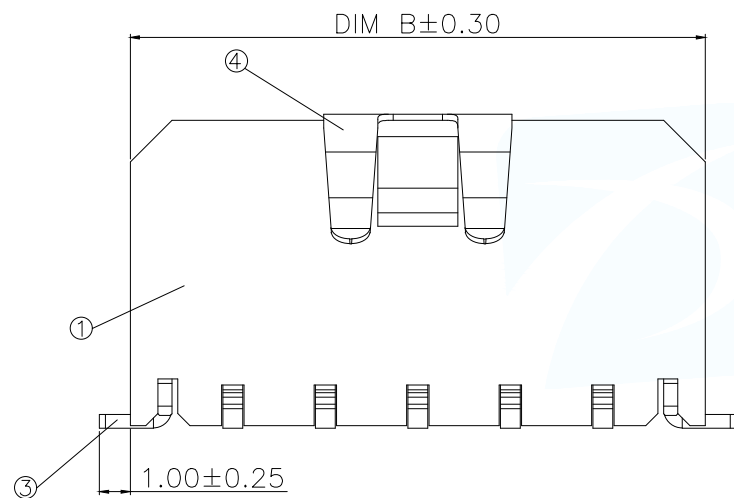
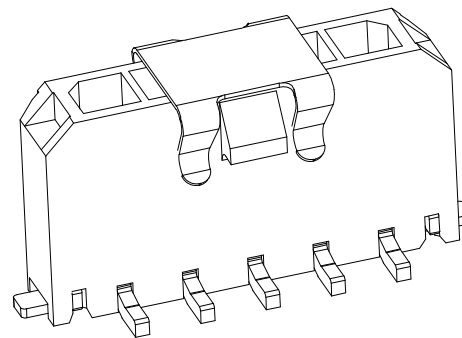
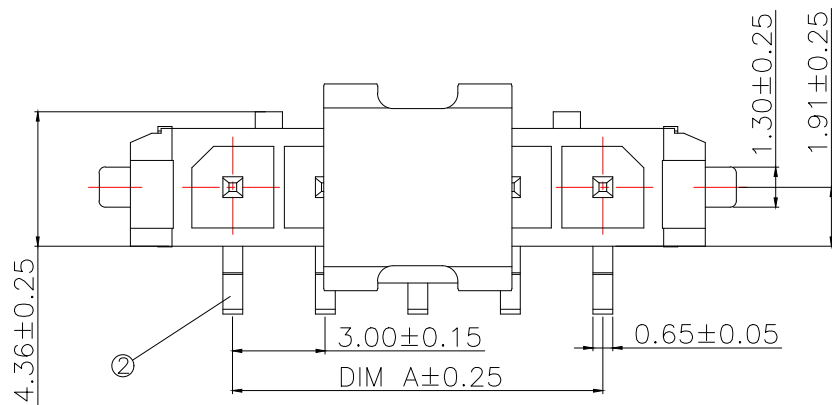


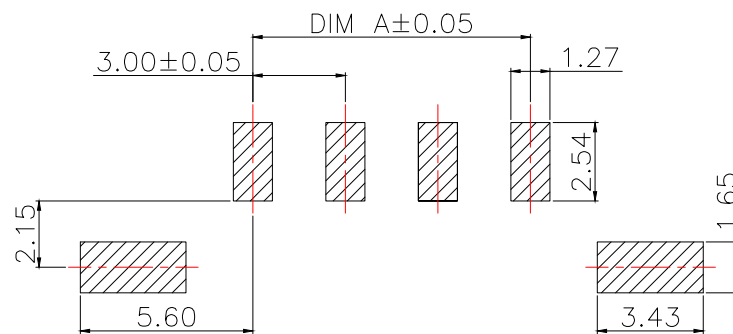


型号	CKT	A	B
WAFER-NX3.0-2PLB	2	3.00	9.65
WAFER-NX3.0-3PLB	3	6.00	12.65
WAFER-NX3.0-4PLB	4	9.00	15.65
WAFER-NX3.0-5PLB	5	12.00	18.65
WAFER-NX3.0-6PLB	6	15.00	21.65
WAFER-NX3.0-7PLB	7	18.00	24.65
WAFER-NX3.0-8PLB	8	21.00	27.65
WAFER-NX3.0-9PLB	9	24.00	30.65
WAFER-NX3.0-10PLB	10	27.00	33.65
WAFER-NX3.0-11PLB	11	30.00	36.65
WAFER-NX3.0-12PLB	12	33.00	39.65

技术指标:

- 1.温度范围: $-25^{\circ}\text{C}\sim 85^{\circ}\text{C}$.
- 2.额定电流: 5.0A AC DC.
- 3.额定电压: 250V AC DC.
- 4.耐电压: 1000V AC/minute.
- 5.接触电阻: $\leq 20\text{m}\Omega$.
- 6.绝缘电阻: $\geq 1000\text{M}\Omega$.

序号	品名	材质
1	MX3.0单排卧式胶芯	LCP UL94V-0 黑色
2	MX3.0单排立式端子	铜合金/表面镀锡
3	MX3.0单排立焊片	铜合金/表面镀锡
4	MX3.0单排立吸盖	不锈钢

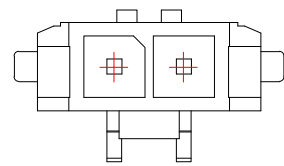


P.C.B Layout

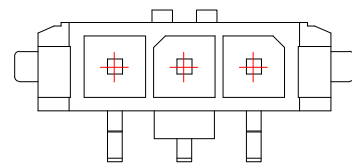
MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: MX3.0 单排立式	
DECIMALS:	ANGLES:	PAR	WAFER-NX3.0-NPLB
X.:±0.50	±1°	DWN	Lucas
X.X:±0.20		CHKD	Ethan
X.XX:±0.10		APVD	Jacob
CUSTOMER COPY		SCALE:1:1	UNIT:MM
		SIZE:A4	SHEET:1F1
			REV:A

ROHS Compliant

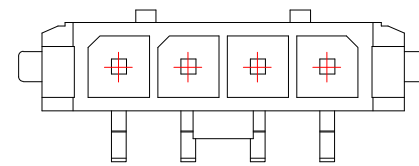
12	13	14	15
MAPX	MODIFICATION	DATE	APPROVE



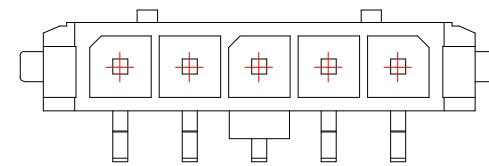
2PIN



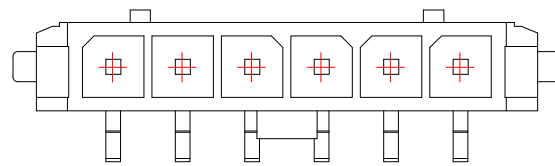
3PIN



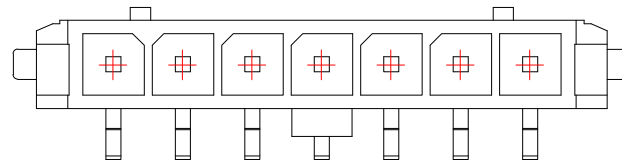
4PIN



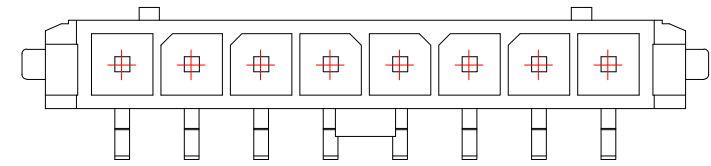
5PIN



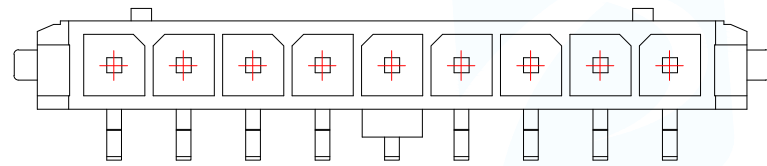
6PIN



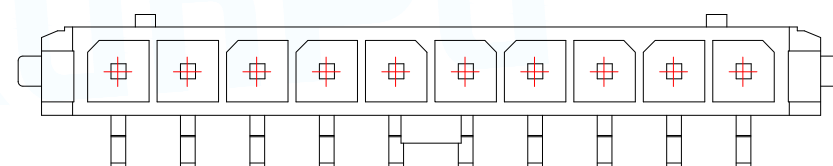
7PIN



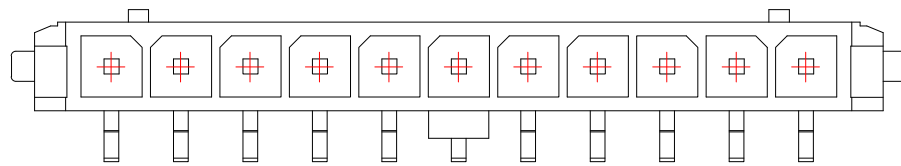
8PIN



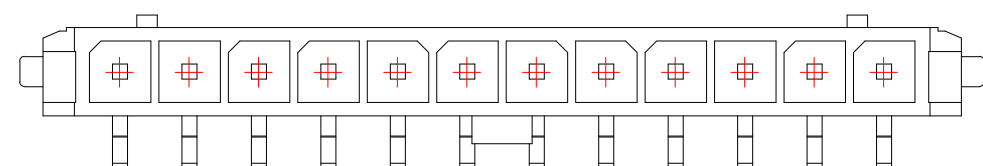
9PIN



10PIN



11PIN



12PIN

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE:
			MX3.0 单排立式
			PAR WAFER-NX3.0-NPLB
			DWN Lucas
DECIMALS:	ANGLES:		CHKD Ethan
X.:±0.50	±1°		APVD Jacob
X.X:±0.20			SCALE:1:1 UNIT:MM
X.XX:±0.10			SIZE:A4 SHEET:1F1
CUSTOMER COPY		REV:A	